

注解:

1. 材料:

- 1-1 主体: LCP E471I+30%玻纤, UL94V-0, 黑色, 符合泰硕HF要求
- 1-2 端子: C5210-EH 料厚=0.12±0.02
- 1-3 铁壳: SUS301-3/4H 料厚=0.15±0.02

2. 电镀:

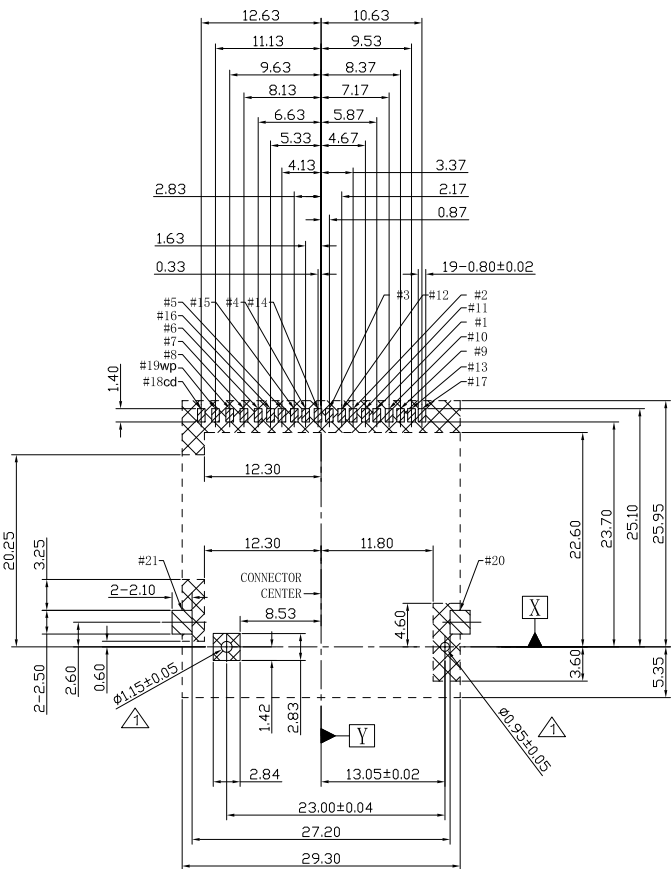
- 2-1 端子:
 - 2-1-1 接触面积: 接触点镀金1U"以上, 镍底50U"以上.
 - 2-1-2 焊锡面积: 镀锡80U"以上, 镍底50U"以上.
- 2-2 铁壳:
 - 2-2-1 焊接面镀金1U"以上, 所有面积镍底镀50U"以上.

3. 焊锡面共面度最大0.1mm







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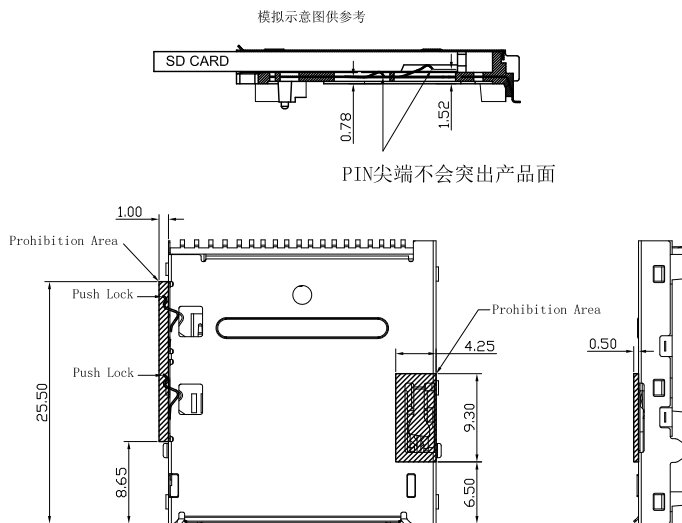
TOLERANCE: X.X ±0.30 X.XX ±0.25 X.XXX ±0.15 X.' ±2' X.X' ±0.5' UNIT: mm [inch] SCALE:1:1 SIZE: A4	DRAWN BY : 陈一鸣	DATE : 2014-02-23	PART NAME: SD PUSH 4.0板上型 5.52H
	CHECKED BY: 马跃	DATE : 2014-02-23	PART NO. HYCW59-SD19-552B
	APPROVED BY: 邱敏	DATE : 2014-02-23	DRAW NO: HYC-SD200903101
			SHEET NO. 1 OF 1



RECOMMEND P.C. BOARD LAYOUT (TOP VIEW)
TOLERANCE UNLESS OTHERWISE SPEC ± 0.05

NOTES:

-  PAD AREA
-  NO PARTS AREA
-  KEEP OUT AREA
-  GND ONLY




NO.	SD NAME	USH-LL NAME
1	CD/DAT3	
2	CMD	
3	VSS1	VSS1
4	VDD	VDD1
5	CLK	
6	VSS2	VSS2
7	DAT0	RCLK+
8	DAT1	RCLK-
9	DAT2	
10		VSS3
11		DO+
12		DO-
13		VSS4
14		VDD2
15		D1-
16		D1+
17		VSS5
18	CD SW	
19	WP SW	
20	GND SW	
21	GND SW	

	W/P CONTACT		C/D CONTACT
	WRITE PROTECT POSITION	WRITE ENABLE POSITION	
CARD UNINSERTION	CLOSE	CLOSE	CLOSE
CARD HALF INSERTION	OPEN	OPEN	CLOSE
CARD INSERTION	CLOSE	OPEN	OPEN



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